

General Description

WSF80N06H use advanced VD MOST technology to provide low RDS(ON), low gate charge, fast switching This device is specially designed to get better ruggedness and suitable to use in Low RDS(on) & FOM Extremely low switching loss Excellent stability and uniformity or Invertors

Features

- Advanced high cell density Trench technology
- •Green Device Available
- •Excellent Cdv/dt effect decline
- •Super Low Gate Charge

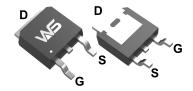
Product Summery

BVDSS	RDSON	ID
60V	8.0mΩ	70A

Applications

- Load switch.
- Battery protection.
- Uninterruptible power supply.

TO-252 Pin Configuration





Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
VGS	Gate-Source Voltage	±20	V
In@Tc=25°C	Continuous Drain Current, Vos @ 10V1	70	А
In@Tc=100°C	Continuous Drain Current, Ves @ 10V1	36	А
In@Ta=25°C	Continuous Drain Current, Ves @ 10V1	10.2	Α
In@Ta=70°C	Continuous Drain Current, Ves @ 10V1	9.5	Α
IDM	Pulsed Drain Current2	100	А
EAS	Single Pulse Avalanche Energy₃	72.2	mJ
IAS	Avalanche Current	38	Α
P n@Tc=25°C	Total Power Dissipation4	52	W
P D@TA=25°C	Total Power Dissipation4	2	W
TSTG	Storage Temperature Range	-55 to 150	°C
Tu	Operating Junction Temperature Range	-55 to 150	°C
R₀JA	Thermal Resistance Junction-Ambient 1	62	°C/W
R⊕JC	Thermal Resistance Junction-Case ₁	2.4	°C/W



Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _G s=0V , I _D =250uA	60	65		V
△BVDSS/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.052		V/°C
RDS(ON)	Static Drain-Source On-Resistance2	V _{GS} =10V , I _D =8A		8.0	10	mΩ
VGS(th)	Gate Threshold Voltage	V V 1 050 A	2.0	2.9	4.0	V
△VGS(th)	V _{GS(th)} Temperature Coefficient	Vgs=Vps, Ip =250uA		-5.76		mV/℃
IDOO	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =25℃			1	uA
IDSS		V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		42		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.5		Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =48V , V _{GS} =4.5V , I _D =15A		28.7		nC
Qgs	Gate-Source Charge			10.5		
Qgd	Gate-Drain Charge			9.9		
Td(on)	Turn-On Delay Time			10.4		- ns
Tr	Rise Time	1		9.2		
Td(off)	Turn-Off Delay Time	T.,		63		
Tf	Fall Time	V _{DD} =30V , V _{GS} =10V , R _G =3.3 Ω, I _D =15A		4.8		
Ciss	Input Capacitance			3240		
Coss	Output Capacitance	7		210		pF
Crss	Reverse Transfer Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		146		
IS	Continuous Source Current _{1,5}				47	Α
ISM	Pulsed Source Current _{2,5}	V _G =V _D =0V , Force Current			100	Α
VSD	Diode Forward Voltage2	V _G s=0V , I _S =1A , T _J =25℃			1.2	V
trr	Reverse Recovery Time	IF=15A , dI/dt=100A/μs , -Tյ=25℃		18		nS
Qrr	Reverse Recovery Charge			14		nC

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2_{\times} The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3. The EAS data shows Max. rating . The test condition is V DD =25V,VGS =10V,L=0.1mH,I AS =38A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



Typical Characteristics

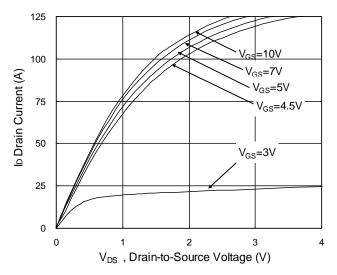


Fig.1 Typical Output Characteristics

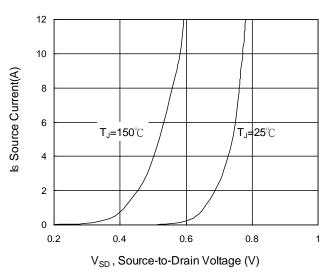


Fig.3 Forward Characteristics of Reverse

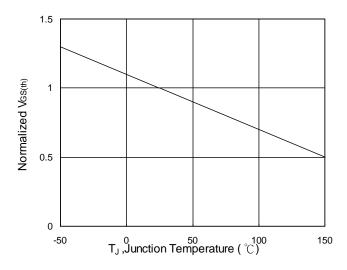


Fig.5 Normalized V_{GS(th)} vs. T_J

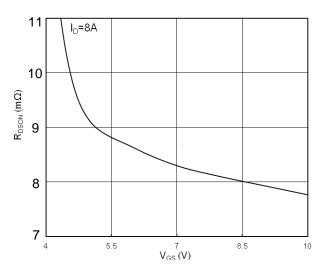


Fig.2 On-Resistance v.s Gate-Source

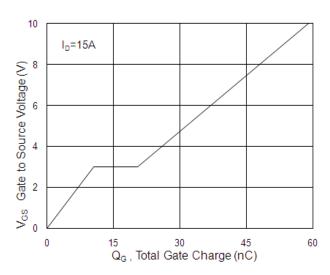


Fig.4 Gate-Charge Characteristics

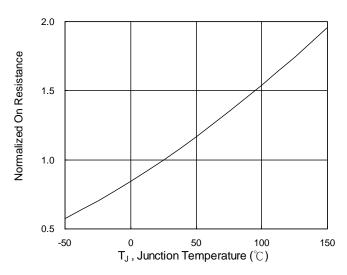
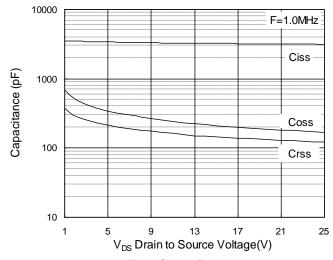


Fig.6 Normalized R_{DSON} vs. T_J





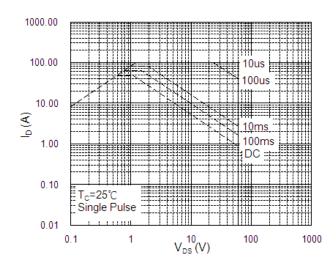


Fig.7 Capacitance

Fig.8 Safe Operating Area

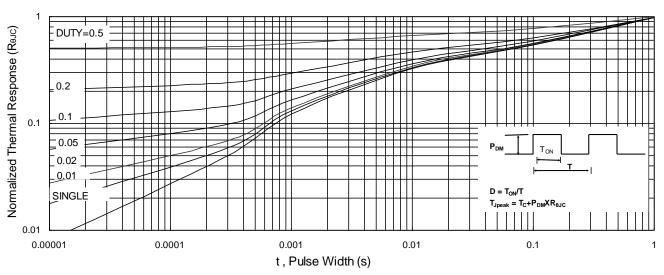
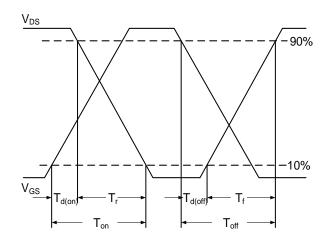


Fig.9 Normalized Maximum Transient Thermal Impedance



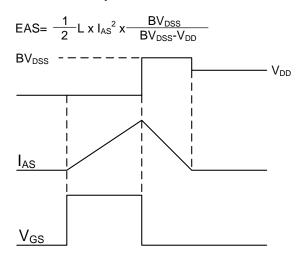


Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



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